

**IN THE CLAIMS:**

1. (Currently Amended) A silicone-based adhesive sheet[[,.]] comprising a first layer ~~of a curable silicone composition on one side of said sheet;~~ and a second layer disposed adjacent to and in contact with said first layer; ~~said second layer comprising a slower-curing silicone composition than said first layer; wherein~~

said first layer comprises

(I) a hydrosilylation-curable silicone composition comprising

(A) an organopolysiloxane having at least two alkenyl groups per molecule,

(B) a filler,

(C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule,

(D) an adhesion promoter, and

(E) a hydrosilylation catalyst;

said second layer comprises

(II) a slower curing hydrosilylation-curable silicone composition different than said hydrosilylation-curable silicone composition (I) of said first layer, said slower curing hydrosilylation-curable silicone composition (II) comprising

(A) an organopolysiloxane having at least two alkenyl groups per molecule,

(B) a filler,

(C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule,

(D) an adhesion promoter, and

(E) a hydrosilylation catalyst; and  
wherein at least one of said hydrosilylation-curable silicone compositions (I) and (II) further  
comprises (F) a curing inhibitor; and  
wherein said slower curing hydrosilylation-curable silicone composition (II) of said second  
layer has a curing time at least five times greater than said hydrosilylation-curable silicone  
composition (I) of said first layer based on the 90% vulcanizing times of said first and second  
layers at 130°C as specified by JIS K 6300.

2. (Currently Amended) The silicone-based adhesive sheet of Claim 1, wherein either of said hydrosilylation-curable silicone compositions (I) and (II) has a plasticity number of from 100 to 800[[.]] as specified by JIS K 6249.

3-4. (Cancelled)

5. (Currently Amended) The silicone-based adhesive sheet of Claim 1, further comprising a protective film disposed on at least one side of [[the]] said silicone-based adhesive sheet and in contact with at least one of said first and second layers.

6. (Previously Presented) The silicone-based adhesive sheet of Claim 1, wherein at least one of said first and second layers is cured.

7-10. (Cancelled)

11. (Withdrawn) A method of bonding a semiconductor chip to a chip attachment component, comprising the steps of:

(1) producing the semiconductor chip by dicing a laminated body comprising a cured silicone layer bonded to a wafer, a layer of curable silicone composition adjacent and firmly bonded to said cured silicone layer, a protective film firmly bonded to said layer of curable silicone composition, and a sheet adhesively attached to said protective film;

(2) peeling said protective film and said sheet from said semiconductor chip;

(3) bonding said semiconductor chip to said chip attachment component by pressing said semiconductor chip to said chip attachment component via said layer of curable silicone composition; and

(4) curing said layer of curable silicone composition.

12. (Withdrawn) The method of Claim 11, wherein the cured silicone layer and the layer of curable silicone composition firmly bonded to the cured silicone layer are formed by applying a first layer of a curable silicone composition (I) to the wafer, applying a second layer of a curable silicone composition (II) to the first layer, the second layer endowed with a lower curing rate than the first layer, and curing the first layer, such that the second layer of composition (II) is prevented from being cured.

13. (Withdrawn) The method of Claim 12, wherein either of said curable silicone compositions (I) and (II) has a plasticity number of from 100 to 800, as specified by JIS K 6249.

14. (Withdrawn) The method of Claim 12, wherein either curable silicone composition (I) or curable silicone composition (II) is a hydrosilylation-curable composition.

15. (Withdrawn) The method of Claim 14, wherein either of said hydrosilylation-curable silicone compositions is a curable silicone composition comprising at least (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

16. (Withdrawn) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the method comprises:

a) fabricating the silicone-based adhesive sheet having a first layer of curable silicone composition (I) and a second layer disposed adjacent to and in contact with said first layer, said second layer comprising a slower curing curable silicone composition (II) than said first layer of composition (I), and

b) curing said first layer of composition (I) so that said second layer of composition (II) remains uncured while said first layer of composition (I) is kept in contact with the semiconductor chip, and said second layer of composition (II) is subsequently cured while kept in contact with the semiconductor chip attachment component.

17. (Withdrawn) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the method comprises:

a) fabricating the silicone-based adhesive sheet having a first layer of curable silicone composition (I) and a second layer disposed adjacent to and in contact with said first layer, said second layer comprising a slower curing curable silicone composition (II) than said first layer of composition (I), and

b) curing said first layer of composition (I) so that said second layer of composition (II) remains uncured while said first layer of composition (I) is kept in contact with the semiconductor chip attachment component, and said second layer of composition (II) is subsequently cured while kept in contact with the semiconductor chip.

18. (Withdrawn) The method of Claim 17, wherein either of said curable silicone compositions has a plasticity number of from 100 to 800, as specified by JIS K 6249.

19. (Withdrawn) The method of Claim 17, wherein either of said curable silicone compositions is a hydrosilylation-curable composition.

20. (Withdrawn) The method of Claim 19, wherein said hydrosilylation-curable silicone composition comprises at least (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

21. (Withdrawn) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the silicone-based adhesive sheet comprises a cured silicone layer and a layer of curable silicone composition disposed adjacent to and in contact with said cured silicone layer; wherein the method comprises:

a) bonding said cured silicone layer so that the layer of curable silicone composition remains uncured while said cured silicone layer is kept in contact with a semiconductor chip, and subsequently

b) curing said layer of curable silicone composition while said layer of curable silicone composition is kept in contact with a semiconductor chip attachment component.

22. (Withdrawn) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the silicone-based adhesive sheet comprises a cured silicone layer and a layer of curable silicone composition disposed adjacent to and in contact with said cured silicone layer; wherein the method comprises:

a) bonding said cured silicone layer so that the layer of curable silicone composition remains uncured while said cured silicone layer is kept in contact with the semiconductor chip attachment component, and subsequently

b) curing said layer of curable silicone composition while said layer of curable silicone composition is kept in contact with said semiconductor chip.

23. (Withdrawn) The method of Claim 22, wherein said curable silicone composition has a plasticity number of from 100 to 800, as specified by JIS K 6249.

24. (Withdrawn) The method of Claim 22, wherein said curable silicone composition is a hydrosilylation-curable composition.

25. (Withdrawn) The method of claim 24, wherein said hydrosilylation-curable silicone composition comprises (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

26. (Withdrawn) A semiconductor device prepared by the method of Claim 11.

27. (Withdrawn) The method of Claim 16, wherein either of said curable silicone compositions has a plasticity number of from 100 to 800, as specified by JIS K 6249.



28. (Withdrawn) The method of Claim 16, wherein either of said curable silicone compositions is a hydrosilylation-curable composition.

29. (Withdrawn) The method of Claim 21, wherein said curable silicone composition has a plasticity number of from 100 to 800, as specified by JIS K 6249.

30. (Withdrawn) The method of Claim 21, wherein said curable silicone composition is a hydrosilylation-curable composition.

31. (Withdrawn) A semiconductor device prepared by the method of Claim 16.

32. (Withdrawn) A semiconductor device prepared by the method of Claim 17.

33. (Withdrawn) A semiconductor device prepared by the method of Claim 21.

34. (Withdrawn) A semiconductor device prepared by the method of Claim 22.

35. (Cancelled)

36. (New) A silicone-based adhesive sheet as set forth in claim 1 wherein both of said layers include said curing inhibitor (F), and said curing inhibitor (F) of said hydrosilylation-curable silicone composition (I) of said first layer is present in an amount different than an amount of said curing inhibitor (F) present in said slower curing hydrosilylation-curable silicone composition (II) of said second layer.

37. (New) A silicone-based adhesive sheet as set forth in claim 1 wherein both of said layers include said curing inhibitor (F), and said curing inhibitor (F) of said hydrosilylation-curable silicone composition (I) of said first layer is of a different type than said curing inhibitor (F) of said slower curing hydrosilylation-curable silicone composition (II) of said second layer, for adjusting curing speed of said layers.

38. (New) A silicone-based adhesive sheet as set forth in claim 1 wherein said slower curing hydrosilylation-curable silicone composition (II) of said second layer has a curing time at least 10 times greater than said hydrosilylation-curable silicone composition (I) of said first layer based on the 90% vulcanizing times of said first and second layers at 130°C as specified by JIS K 6300.